

Amendments to the Claims:

This listing of claims replaces any previous listing of claims.

1-39. (Cancelled)

40. (New) A mold for molding a package for at least one die bonded to a substrate, the mold comprising a first mold portion that defines a package cover for encapsulating the at least one die and a portion of a surface of the substrate to which the die is bonded, and a second mold portion that defines a rib that projects outwardly from a surface of the substrate opposite the surface of the substrate to which the at least one die is bonded.

41. (New) The mold of claim 40, wherein the first mold portion and the second mold portion define package covers and ribs for a plurality of die bonded to the substrate.